

Material Composition Specification

SOT-23F Case



Device average mass **11.0 mg**
 Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.64%	0.07	Si	7440-21-3	0.64%	0.07	6,364
bond wire	gold	0.2%	0.02	Au	7440-57-5	0.2%	0.022	2,000
leadframe	Cu alloy w/ silver plating	38.38%	4.22	Cu	7440-50-8	37.65%	4.141	376,455
				Fe	7439-89-6	0.04%	0.004	364
				Ag	7440-22-4	0.7%	0.077	7,000
die attach	silver epoxy	0.43%	0.05	Ag	7440-22-4	0.32%	0.035	3,182
				epoxy resin	Proprietary	0.11%	0.012	1,091
encapsulation*	EMC	59.47%	6.54	silica	7631-86-9	42.89%	4.718	428,909
				epoxy resin	Proprietary	14.95%	1.644	149,455
				Sb ₂ O ₃	1309-64-4	1.19%	0.131	11,909
				TBBA	79-94-7	0.3%	0.033	3,000
				carbon	1333-86-4	0.15%	0.016	1,455
	EMC GREEN	59.47%	6.54	silica	60676-86-0	39.34%	4.327	393,364
				epoxy resin	37382079-9	6.82%	0.75	68,182
				phenol resin	9003-35-4	6.82%	0.75	68,182
				carbon black	1333-86-4	0.31%	0.034	3,091
				metal hydroxide	1309-42-8	6.19%	0.681	61,909
plating	matte tin	0.88%	0.1	Sn	7440-31-5	0.88%	0.097	8,818

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R6 (3-June 2011)